

L Number	Hits	Search Text	DB	Time stamp
1	1787	(438/106,123).CCLS.	USPAT	2004/05/27 08:33
2	598	(257/783).CCLS.	USPAT	2004/05/27 08:53
3	1949	semiconductor and (chip or die) and adhesive and stack	USPAT	2004/05/27 08:56
5	1189	semiconductor and (chip or die) and adhesive and stack	US-PGPUB	2004/05/27 08:56
4	1949	semiconductor and (chip or die) and adhesive and stack	USPAT	2004/05/27 08:57
6	1189	semiconductor and (chip or die) and adhesive and stack	US-PGPUB	2004/05/27 08:57
7	2	semiconductor and (chip or die) and adhesive and stack	EPO	2004/05/27 08:57
8	8	semiconductor and (chip or die) and adhesive and stack	JPO	2004/05/27 08:57
9	138	semiconductor and (chip or die) and adhesive and stack	DERWENT	2004/05/27 08:57
10	2	semiconductor and (chip or die) and adhesive and stack	IBM_TDB	2004/05/27 08:57